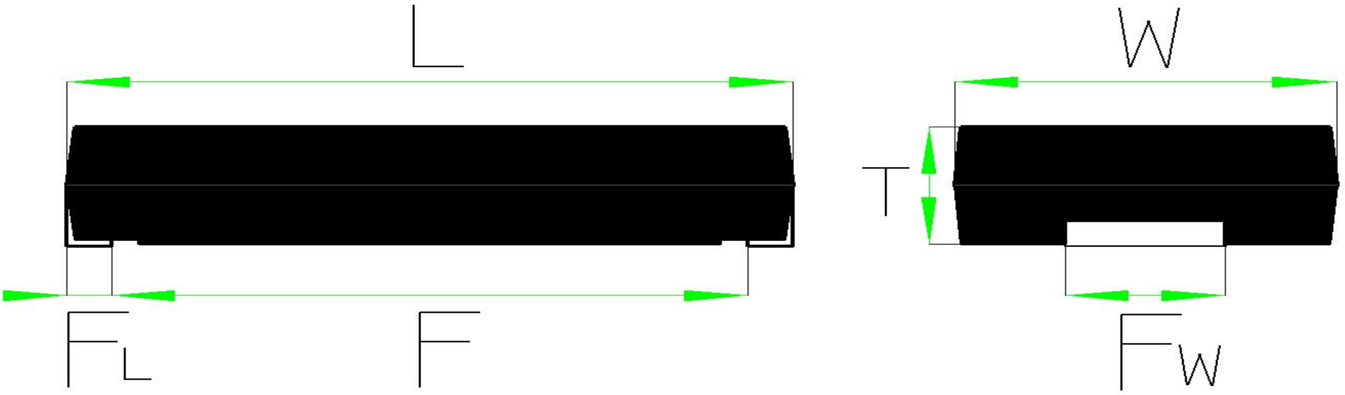
o§̀o§̬ oC̉

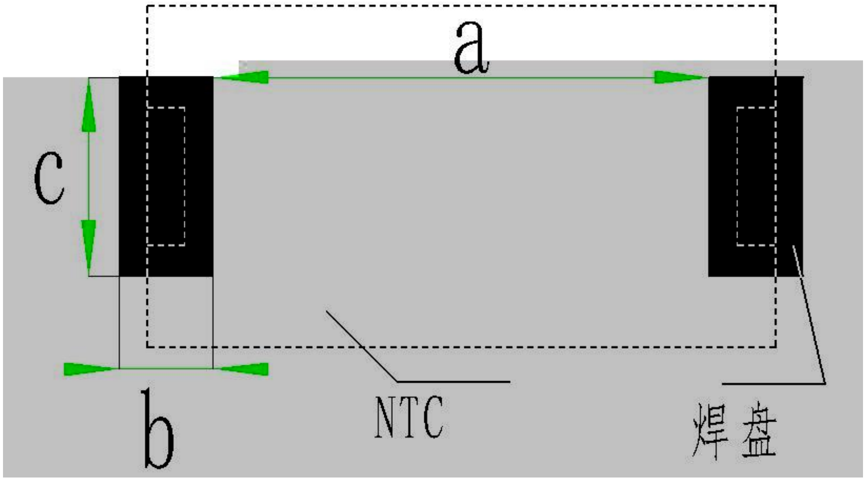
o§̰O̬

Ω Ω μ



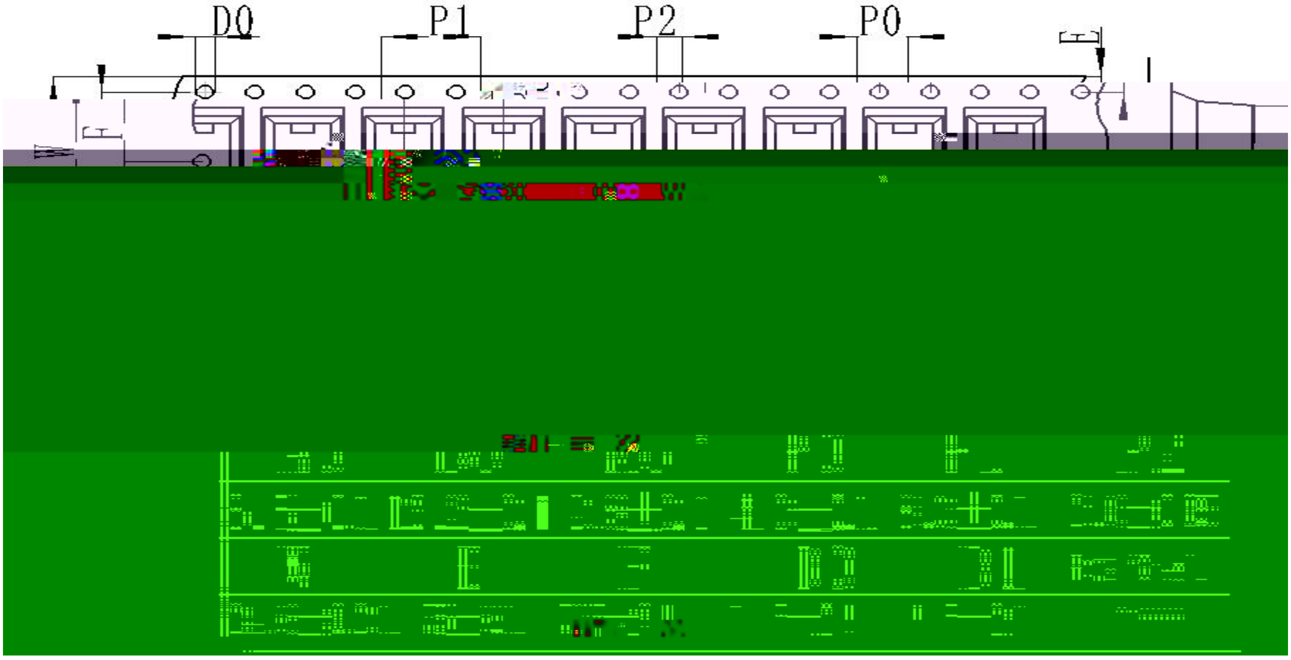
L
W
T
FL
F
FW

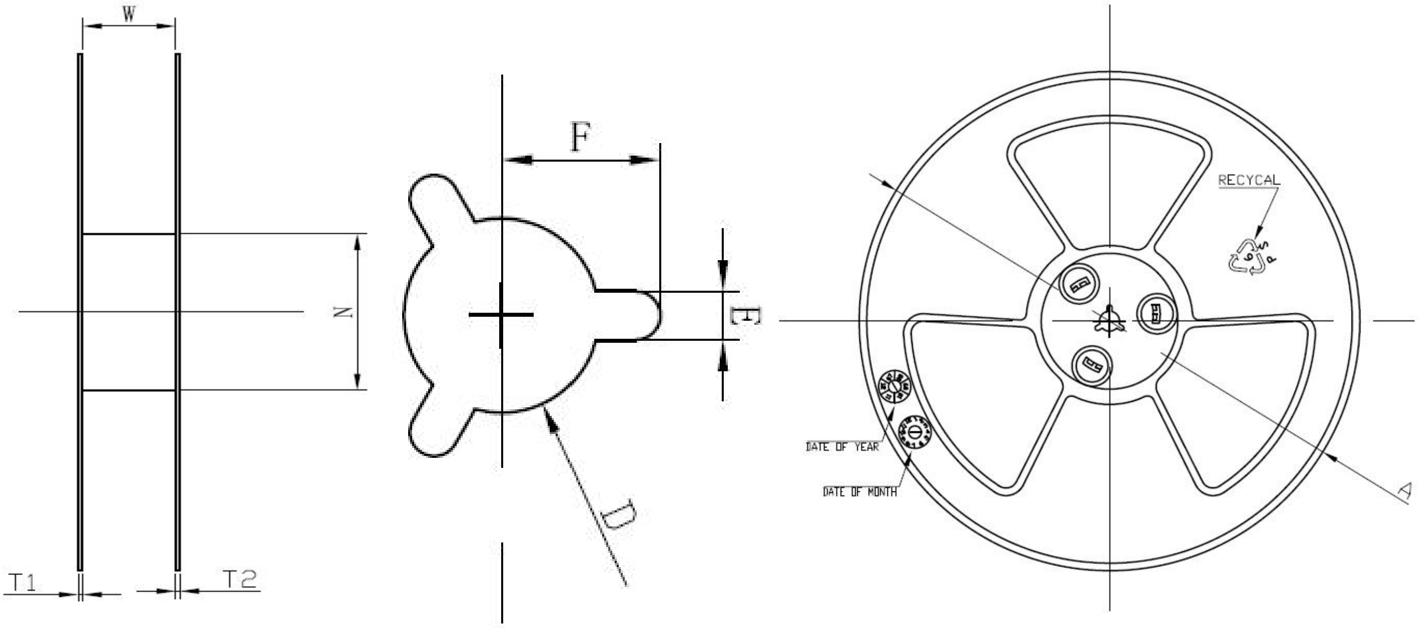
	±	±	±	±	±	±



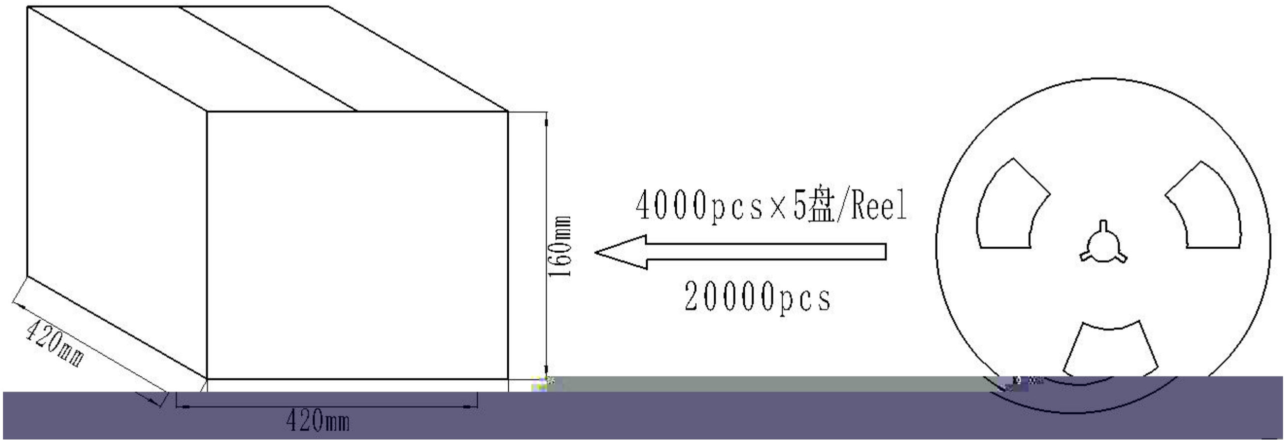
a
c
b
NTC
焊盘


①
②
③
④

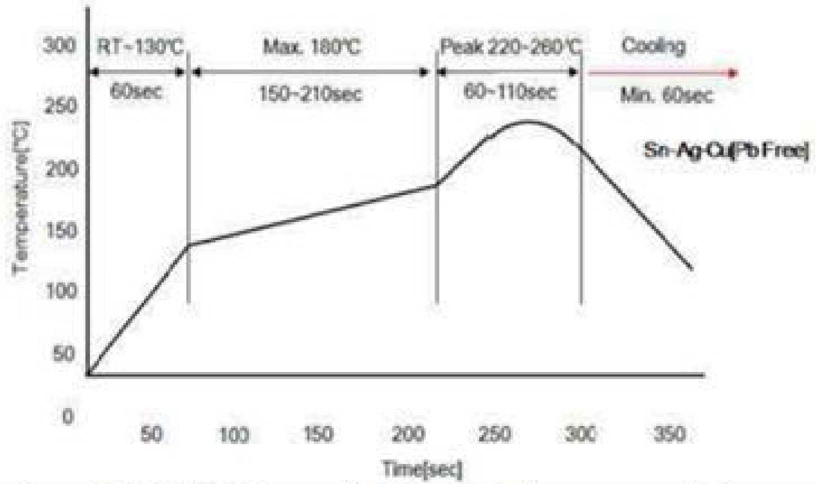

D0
P1
P2
P0
E
F
W


W
N
T1
T2
F
E
D
RECYCAL
DATE OF YEAR
DATE OF MONTH
A

	±	±	±	±	±	±	±	±



☆回流焊接曲线

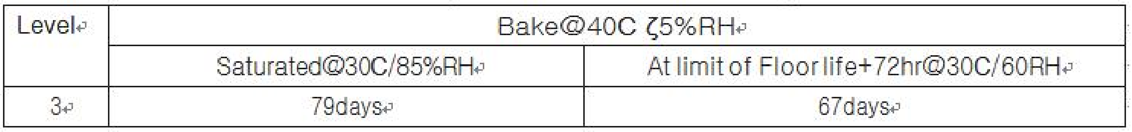


温区		温度范围（℃)	时间 (sec)	备注
a	固化	RT~130	60	焊锡: Sn-Ag-Cu 高温时间: ＜ 10 sec
b	预热	180 max	150~210	
c	焊接	220~260(260 max)	60~110	
d	冷却	220~RT	60 min	

当焊接温度低于锡的熔点时，贴片镀锡端子的可焊性将下降。使用之前请确认贴片镀锡电极的可焊性

焊接区出风口及内部空间最高温度不能超过 280℃ [illegible]

[illegible]



Level	Bake@40C ζ5%RH	
	Saturated@30C/85%RH	At limit of Floor life+72hr@30C/60RH
3	79days	67days